

HMC430LP4 / 430LP4E

v06.1106



MMIC VCO w/ BUFFER AMPLIFIER, 5.0 - 5.5 GHz

Typical Applications

Low noise MMIC VCO w/Buffer Amplifier for C-Band applications such as:

- 802.11a & HiperLAN WLAN
- VSAT Radios
- UNII & Point-to-Point Radios

Features

Pout: +2 dBm

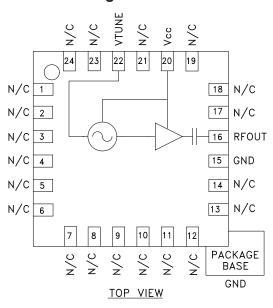
Phase Noise: -103 dBc/Hz @100 kHz

No External Resonator Needed

Single Supply: 3V @ 27 mA

16mm² Leadless SMT Package

Functional Diagram



General Description

The HMC430LP4 & HMC430LP4E are GaAs InGaP Heterojunction Bipolar Transistor (HBT) MMIC VCOs with integrated resonators, negative resistance devices, varactor diodes, and buffer amplifiers. The VCO's phase noise performance is excellent over temperature, shock, vibration and process due to the oscillator's monolithic structure. Power output is 2 dBm typical from a 3V supply voltage. The voltage controlled oscillator is packaged in a low cost leadless QFN 4 x 4 mm surface mount package.

Electrical Specifications, $T_A = +25^{\circ}$ C, Vcc = +3V

Parameter	Min.	Тур.	Max.	Units
Frequency Range	5.0 - 5.5			GHz
Power Output	-1	2		dBm
SSB Phase Noise @ 100 kHz Offset, Vtune= +5V @ RF Output		-103		dBc/Hz
Tune Voltage (Vtune)	0		10	V
Supply Current (Icc) (Vcc= +3.0V)		27		mA
Tune Port Leakage Current			10	μΑ
Output Return Loss		6		dB
Harmonics 2nd 3rd		-15 -25		dBc dBc
Pulling (into a 2.0:1 VSWR)		12		MHz pp
Pushing @ Vtune= +5V		12		MHz/V
Frequency Drift Rate		0.8		MHz/°C

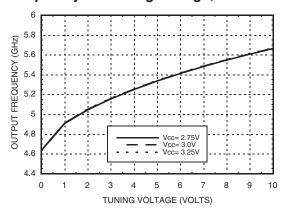


v06.1106

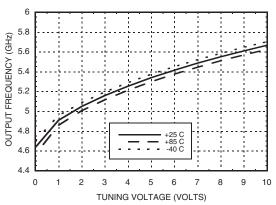


MMIC VCO w/ BUFFER AMPLIFIER, 5.0 - 5.5 GHz

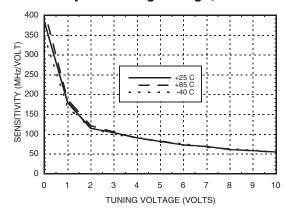
Frequency vs. Tuning Voltage, T= 25°C



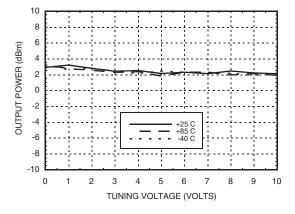
Frequency vs. Tuning Voltage, Vcc= +3V



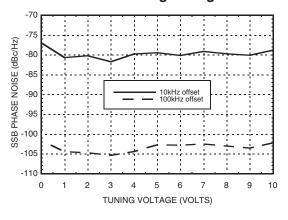
Sensitivity vs. Tuning Voltage, Vcc= +3V



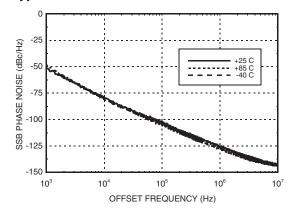
Output Power vs.
Tuning Voltage, Vcc= +3V



Phase Noise vs. Tuning Voltage



Typical SSB Phase Noise @ Vtune= +5V



v06.1106



MMIC VCO w/ BUFFER AMPLIFIER, 5.0 - 5.5 GHz

Absolute Maximum Ratings

Vcc	+3.5 Vdc
Vtune	0 to +11V
Junction Temperature	135 °C
Continuous Pdiss (T = 85°C) (derate 2.1 mW/°C above 85°C)	104 mW
Thermal Resistance (junction to ground paddle)	482 °C/W
Storage Temperature	-65 to +150 °C
Operating Temperature	-40 to +85 °C
ESD Sensitivity (HBM)	Class 1A

Typical Supply Current vs. Vcc

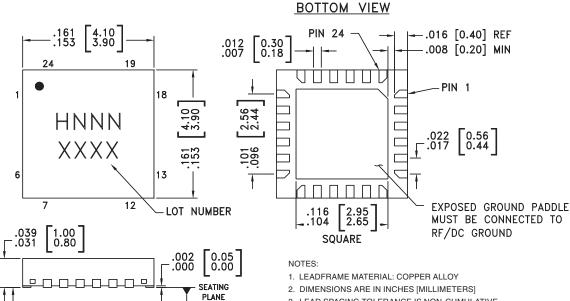
Vcc (V)	Icc (mA)
2.75	19
3.0	27
3.25	34

Note: VCO will operate over full voltage range shown above.



ELECTROSTATIC SENSITIVE DEVICE OBSERVE HANDLING PRECAUTIONS

Outline Drawing



-C-

- 3. LEAD SPACING TOLERANCE IS NON-CUMULATIVE.
- 4. PAD BURR LENGTH SHALL BE 0.15mm MAXIMUM.
 PAD BURR HEIGHT SHALL BE 0.05mm MAXIMUM.
- 5. PACKAGE WARP SHALL NOT EXCEED 0.05mm.
- 6. ALL GROUND LEADS AND GROUND PADDLE MUST BE SOLDERED TO PCB RF GROUND.
- 7. REFER TO HITTITE APPLICATION NOTE FOR SUGGESTED LAND PATTERN.

Package Information

⊃|.003[0.08]|C

Part Number	Package Body Material	Lead Finish	MSL Rating	Package Marking [3]
HMC430LP4	Low Stress Injection Molded Plastic	Sn/Pb Solder	MSL1 [1]	H430 XXXX
HMC430LP4E	RoHS-compliant Low Stress Injection Molded Plastic	100% matte Sn	MSL1 [2]	H430 XXXX

- [1] Max peak reflow temperature of 235 $^{\circ}\text{C}$
- [2] Max peak reflow temperature of 260 °C
- [3] 4-Digit lot number XXXX



v06.1106

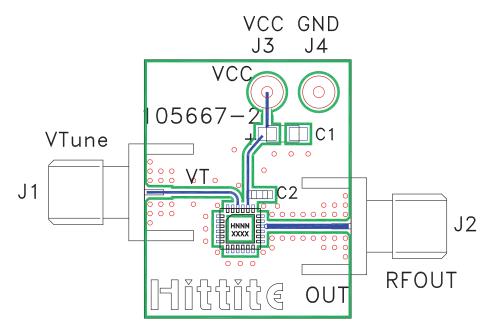


MMIC VCO w/ BUFFER AMPLIFIER, 5.0 - 5.5 GHz

Pin Descriptions

Pin Number	Function	Description	Interface Schematic
1- 14, 17 - 19, 21, 23, 24	N/C	No Connection	
15	GND	This pin must be connected to RF & DC ground.	O GND
16	RFOUT	RF output (AC coupled)	— —O RFOUT
20	Vcc	Supply Voltage Vcc= 3V	Vcc O26pF
22	VTUNE	Control Voltage Input. Modulation port bandwidth dependent on drive source impedance.	7.5nH 1500 5.2pF
	GND	Package bottom has an exposed metal paddle that must be RF & DC grounded.	○ GND =

Evaluation PCB



List of Materials for Evaluation PCB 105706 [1]

Item	Description
J1 - J2	PCB Mount SMA RF Connector
J3 - J4	DC Pin
C1	4.7 μF Tantalum Capacitor
C2	10,000 pF Capacitor, 0603 Pkg.
U1	HMC430LP4 / HMC430LP4E VCO
PCB [2]	105667 Eval Board

[1] Reference this number when ordering complete evaluation PCB

[2] Circuit Board Material: Rogers 4350

The circuit board used in the final application should use RF circuit design techniques. Signal lines should have 50 ohm impedance while the package ground leads and exposed paddle should be connected directly to the ground plane similar to that shown. A sufficient number of via holes should be used to connect the top and bottom ground planes. The evaluation circuit board shown is available from Hittite upon request.



HMC430LP4 / 430LP4E

v06.1106



Notes:

MMIC VCO w/ BUFFER AMPLIFIER, 5.0 - 5.5 GHz

11